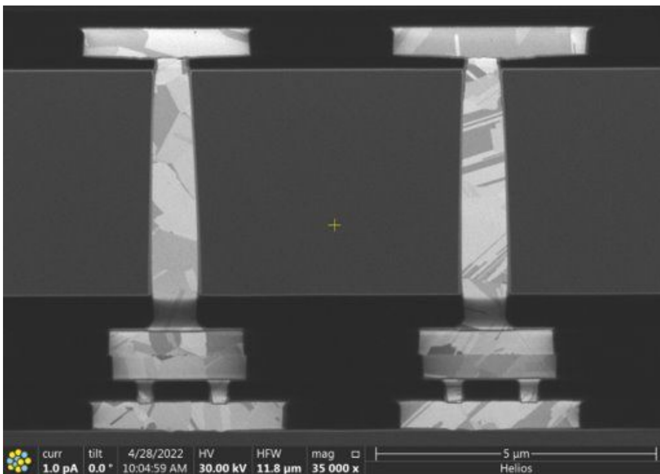
VIZTA

3D HYBRID BONDING

« SELLING » STATEMENT:

A novel and attractive 3D stacking technology, enabling improved electrical performances with high yield for applications such as CMOS Image Sensor (CIS), memories and displays.



Integration of HD TSV within a hybrid bonding scheme

KEY FEATURES

A 3D stacking enabling significant improvements

- Decrease of electronic component surface.
- Decrease of Power consumption.
- Higher interconnection speed.

Demonstrated within VIZTA:

- Feasibility of 2 Layers Test Vehicle using Face-to-Back hybrid bonding and High Density TSV.
- Good morphological and promising electrical results.

1 peer-review publication targeted

- Electronics Packaging Technology Conference (EPTC 2023)

Interesting perspectives through research continuation

- 3 layers CIS functional device with integrated sensor, logic and memory levels.

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